

# **3000W Surface Mount Transient Voltage Suppressor**

#### **FEATURES**

- AEC-Q101 qualified
- Moisture sensitivity level: level 1, per J-STD-020
- Meets IEC 61000-4-2 (Level: 4) / ISO 10605 (Level: L4)
- Meets ISO 7637-2 (Pulse 1/2a/2b/3a/3b)
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Switching mode power supply (SMPS)
- Motor for BLDC
- Lighting application
- Battery Management System
- Automotive

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Weight: 0.21g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
V <sub>WM</sub>	18	V			
V <sub>BR</sub>	21.1	V			
P <sub>PPM</sub>	3000	W			
T <sub>J MAX</sub>	175	°C			
Polarity	Uni-directional				
Package	DO-214AB (SMC)				





DO-214AB (SMC)

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Non-repetitive peak impulse power dissipation with 10/1000µs waveform <sup>(1)</sup>	P <sub>PPM</sub>	3000	W	
Steady state power dissipation at $T_L$ =25°C <sup>(2)</sup>	P <sub>D</sub>	8.5	W	
Peak forward surge current 8.3 ms single half sine-wave	I <sub>FSM</sub>	300	А	
Junction temperature	TJ	-55 to +175	°C	
Storage temperature	T <sub>STG</sub>	-55 to +175	°C	

Notes:

1. Non-repetitive current pulse per fig. 3 and derated above  $T_A$ =25°C per fig. 1

2. Units mounted on PCB (16mm x 16mm Cu pad test board)



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance per diode	R <sub>ejl</sub>	17	°C/W		
Junction-to-ambient thermal resistance per diode	R <sub>eJA</sub>	50	°C/W		
Junction-to-case thermal resistance per diode	R <sub>eJC</sub>	10	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)											
Part Marking	I <sub>R</sub> max at V <sub>WM</sub>		$V_{BR}$ at $I_{T}^{(1)}$			V <sub>c</sub> at Ι <sub>ΡΡΜ</sub> 10/1000 μs		R <sub>D</sub> 10/1000 µs	<b>αT</b> <sup>(2)</sup>		
number	code			min	typ	max	Ι <sub>Τ</sub>	max			max
		μA	V		V		mA	V <sup>(3)</sup>	А	Ω	10 <sup>-4</sup> /°C
3KSMC21AH	3K21A	3	18	20	21.1	22.2	1	29.2	102.7	0.079	9.2

Note:

1. Pulse test: tp < 30 ms

2. To calculate  $V_{BR}$  or  $V_C$  versus junction temperature, use following formulas:

 $V_{BR}$  at  $T_J = V_{BR}$  at 25°C x (1 +  $\alpha$ T x ( $T_J$ -25))

 $V_C$  at  $T_J = V_C$  at 25°C x (1 +  $\alpha$ T x ( $T_J$ -25))

3. To calculate maximum clamping voltage at other surge level, use the following formula:  $V_{Cmax} = V_C - R_D x (I_{PP} - I_{PPappli})$  where  $I_{PPappli}$  is the surge current in the application.

ORDERING INFORMATION				
ORDERING CODE	PACKAGE	PACKING		
3KSMC21AH V7G	SMC	850 / 7" reel		
3KSMC21AH V6G	SMC	3,000 / 13" reel		



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

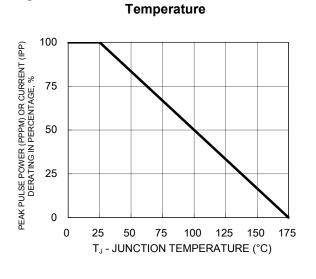


Fig.1 Pulse Power or Current vs. Initial Junction

Fig.3 Clamping Power Pulse Waveform

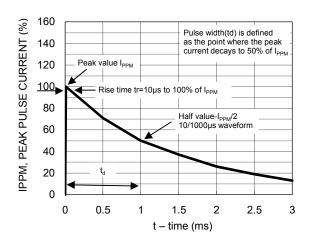


Fig.5 Typical Transient Thermal Impedance

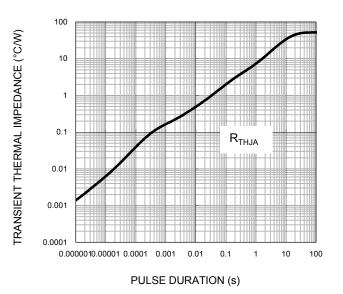


Fig.2 Steady State Power Derating

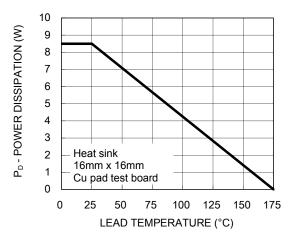


Fig.4 Typical Junction Capacitance

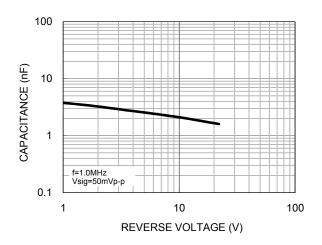
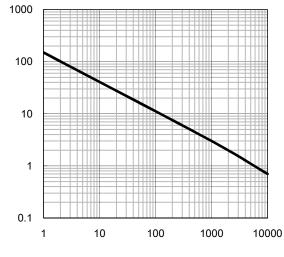


Fig.6 Peak Pulse Power Rating Cure



tp, PULSE WIDTH (µs)

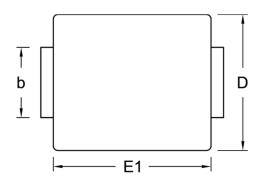
Ppom. PEAK PULSE POWER (KW)

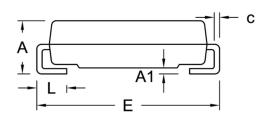
Taiwan Semiconductor



#### PACKAGE OUTLINE DIMENSIONS

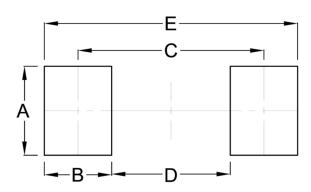
DO-214AB (SMC)





DIM.	Unit	(mm)	Unit (inch)		
	Min.	Max.	Min.	Max.	
A	2.00	2.62	0.079	0.103	
A1	-	0.20	-	0.008	
b	2.90	3.20	0.114	0.126	
с	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

### SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

#### **MARKING DIAGRAM**



Note: Cathode band for unidirectional products only

P/N	= Marking Code
YW	= Date Code
F	= Factory Code



Taiwan Semiconductor

## Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Taiwan Semiconductor: 3KSMC21AH V7G